

To our customers,

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## Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

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# MOS FIELD EFFECT TRANSISTOR NP90N055VDG

## SWITCHING N-CHANNEL POWER MOS FET

### DESCRIPTION

The NP90N055VDG is N-channel MOS Field Effect Transistor designed for high current switching applications.

### ORDERING INFORMATION

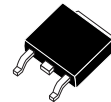
| PART NUMBER                       | LEAD PLATING  | PACKING          | PACKAGE                     |
|-----------------------------------|---------------|------------------|-----------------------------|
| NP90N055VDG-E1-AY <sup>Note</sup> | Pure Sn (Tin) | Tape 2500 p/reel | TO-252 (MP-3ZP) typ. 0.27 g |
| NP90N055VDG-E2-AY <sup>Note</sup> |               |                  |                             |

**Note** Pb-free (This product does not contain Pb in external electrode.)

### FEATURES

- Logic level
- Super low on-state resistance  
 $R_{DS(on)1} = 6.0 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 45 \text{ A)}$   
 $R_{DS(on)2} = 10.5 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 35 \text{ A)}$
- High current rating  
 $I_{D(DC)} = \pm 90 \text{ A}$
- Low input capacitance  
 $C_{iss} = 4600 \text{ pF TYP.}$
- Designed for automotive application and AEC-Q101 qualified

(TO-252)



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

|   |                       |             |    |
|---|-----------------------|-------------|----|
| Drain to Source Voltage (V <sub>GS</sub> = 0 V) | V <sub>bss</sub>      | 55          | V  |
| Gate to Source Voltage (V <sub>DS</sub> = 0 V)  | V <sub>gss</sub>      | ±20         | V  |
| Drain Current (DC) (T <sub>C</sub> = 25°C)      | I <sub>D(DC)</sub>    | ±90         | A  |
| Drain Current (pulse) <sup>Note1</sup>          | I <sub>D(pulse)</sub> | ±200        | A  |
| Total Power Dissipation (T <sub>C</sub> = 25°C) | P <sub>T1</sub>       | 105         | W  |
| Total Power Dissipation (T <sub>A</sub> = 25°C) | P <sub>T2</sub>       | 1.2         | W  |
| Channel Temperature                             | T <sub>ch</sub>       | 175         | °C |
| Storage Temperature                             | T <sub>stg</sub>      | -55 to +175 | °C |
| Repetitive Avalanche Current <sup>Note2</sup>   | I <sub>AR</sub>       | 33          | A  |
| Repetitive Avalanche Energy <sup>Note2</sup>    | E <sub>AR</sub>       | 111         | mJ |

**Notes 1.** PW ≤ 10 μs, Duty Cycle ≤ 1%

**2.** T<sub>ch</sub> ≤ 150°C, R<sub>G</sub> = 25 Ω

### THERMAL RESISTANCE

|                                       |                       |      |      |
|---------------------------------------|-----------------------|------|------|
| Channel to Case Thermal Resistance    | R <sub>th(ch-C)</sub> | 1.43 | °C/W |
| Channel to Ambient Thermal Resistance | R <sub>th(ch-A)</sub> | 125  | °C/W |

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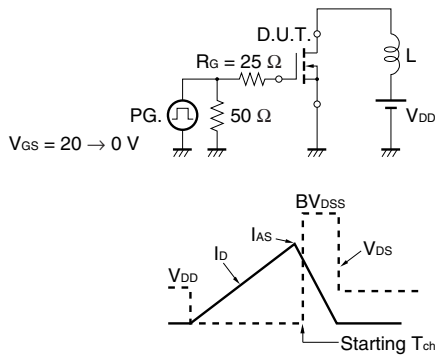
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**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

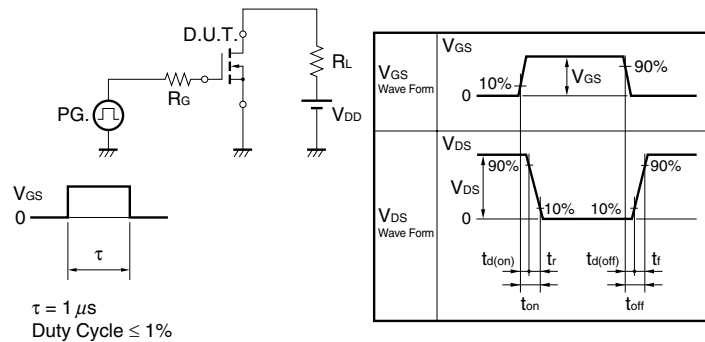
| CHARACTERISTICS                                 | SYMBOL               | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|---|----------------------|---|------|------|------|------|
| Zero Gate Voltage Drain Current                 | I <sub>DSS</sub>     | V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V               |      |      | 1    | μA   |
| Gate Leakage Current                            | I <sub>GSS</sub>     | V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V              |      |      | ±100 | nA   |
| Gate to Source Threshold Voltage                | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA | 1.4  |      | 2.5  | V    |
| Forward Transfer Admittance <b>Note</b>         | y <sub>fs</sub>      | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 45 A                | 30   | 66   |      | S    |
| Drain to Source On-state Resistance <b>Note</b> | R <sub>DS(on)1</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 45 A               |      | 4.8  | 6.0  | mΩ   |
|   | R <sub>DS(on)2</sub> | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 35 A              |      | 6.0  | 10.5 | mΩ   |
| Input Capacitance                               | C <sub>iss</sub>     | V <sub>DS</sub> = 25 V,                                     |      | 4600 | 6900 | pF   |
| Output Capacitance                              | C <sub>oss</sub>     | V <sub>GS</sub> = 0 V,                                      |      | 390  | 590  | pF   |
| Reverse Transfer Capacitance                    | C <sub>rss</sub>     | f = 1 MHz   |      | 240  | 440  | pF   |
| Turn-on Delay Time                              | t <sub>d(on)</sub>   | V <sub>DD</sub> = 28 V, I <sub>D</sub> = 45 A,              |      | 17   | 34   | ns   |
| Rise Time                                       | t <sub>r</sub>       | V <sub>GS</sub> = 10 V,                                     |      | 13   | 33   | ns   |
| Turn-off Delay Time                             | t <sub>d(off)</sub>  | R <sub>G</sub> = 0 Ω  |      | 76   | 152  | ns   |
| Fall Time                                       | t <sub>f</sub>       |   |      | 7    | 18   | ns   |
| Total Gate Charge                               | Q <sub>G</sub>       | V <sub>DD</sub> = 44 V,                                     |      | 90   | 135  | nC   |
| Gate to Source Charge                           | Q <sub>GS</sub>      | V <sub>GS</sub> = 10 V,                                     |      | 13   |      | nC   |
| Gate to Drain Charge                            | Q <sub>GD</sub>      | I <sub>D</sub> = 90 A                                       |      | 26   |      | nC   |
| Body Diode Forward Voltage <b>Note</b>          | V <sub>F(S-D)</sub>  | I <sub>F</sub> = 90 A, V <sub>GS</sub> = 0 V                |      | 0.9  | 1.5  | V    |
| Reverse Recovery Time                           | t <sub>rr</sub>      | I <sub>F</sub> = 90 A, V <sub>GS</sub> = 0 V,               |      | 38   |      | ns   |
| Reverse Recovery Charge                         | Q <sub>rr</sub>      | di/dt = 100 A/μs  |      | 45   |      | nC   |

**Note** Pulsed test

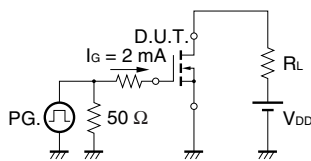
**TEST CIRCUIT 1 AVALANCHE CAPABILITY**



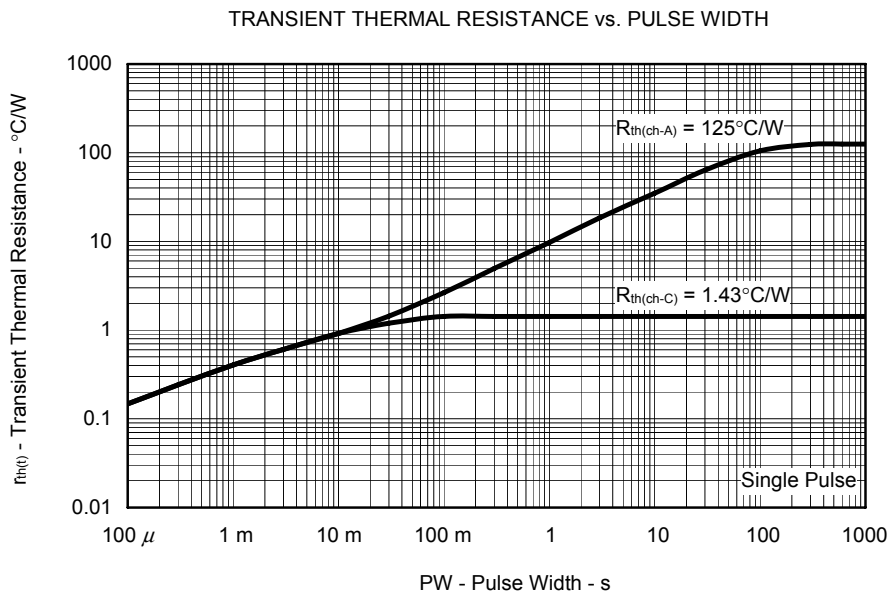
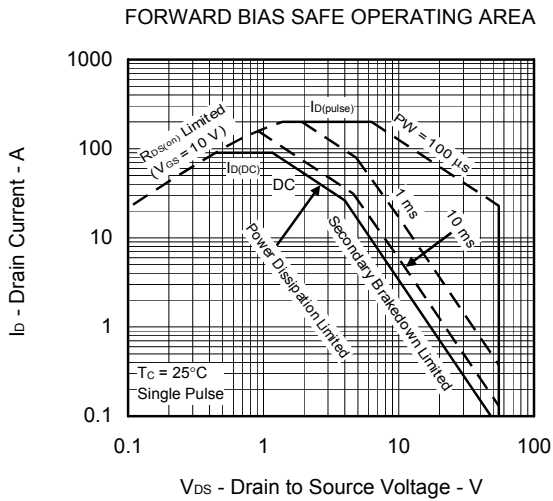
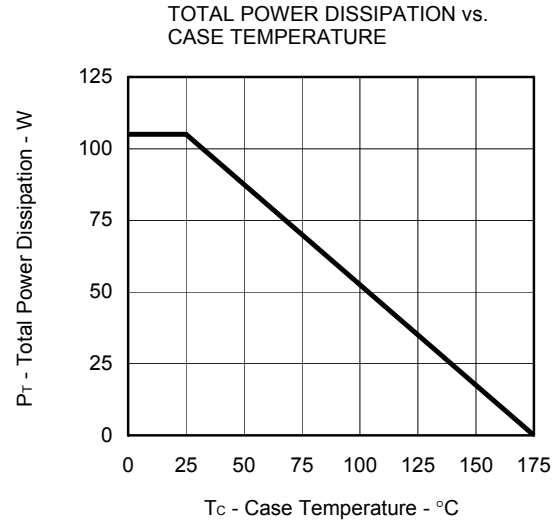
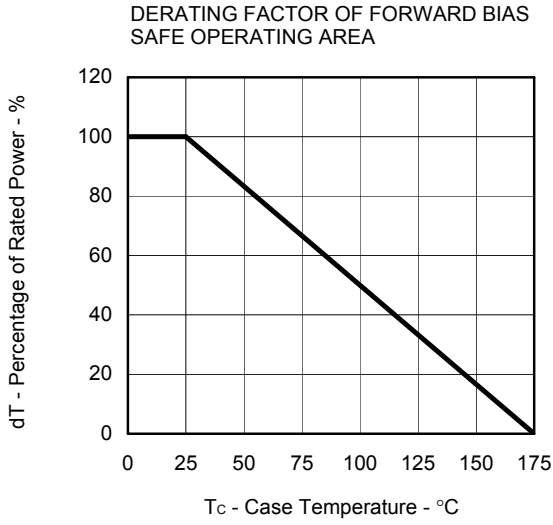
**TEST CIRCUIT 2 SWITCHING TIME**



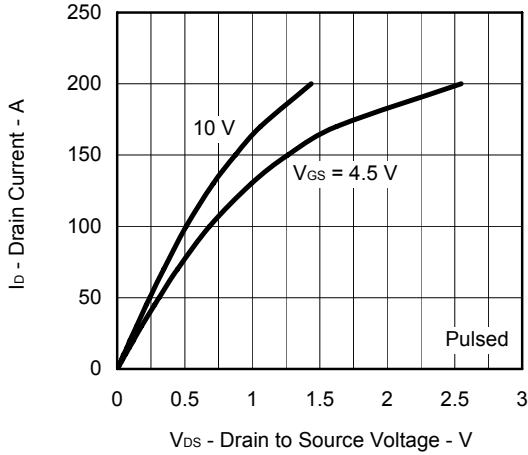
**TEST CIRCUIT 3 GATE CHARGE**



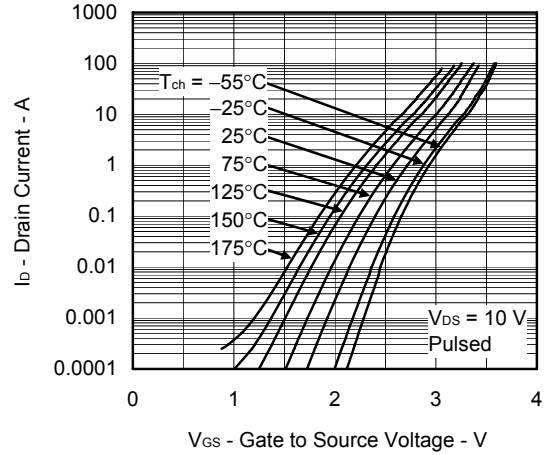
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)



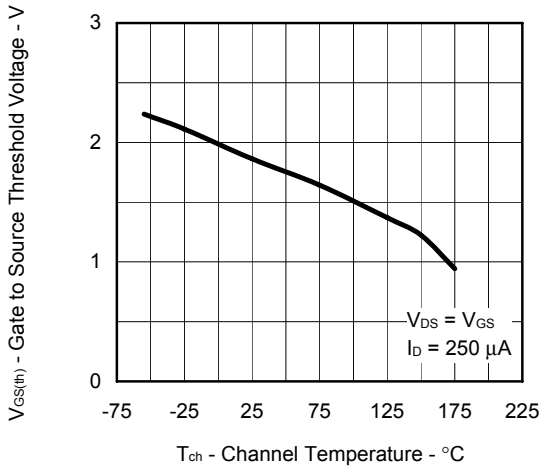
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



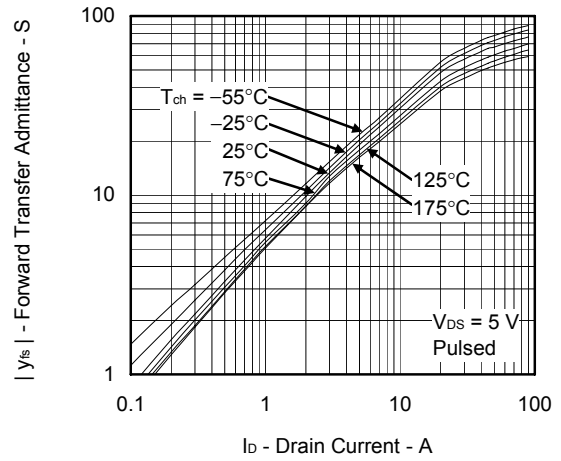
FORWARD TRANSFER CHARACTERISTICS



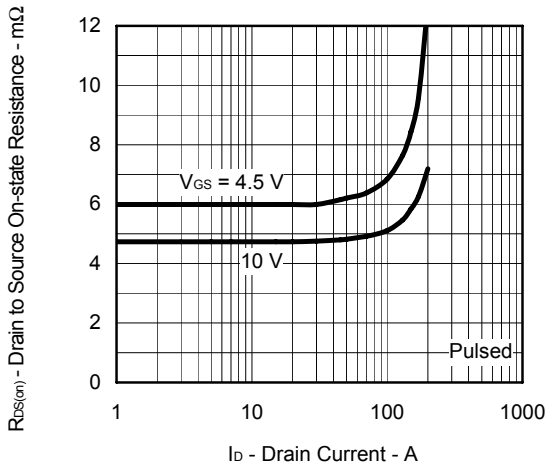
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



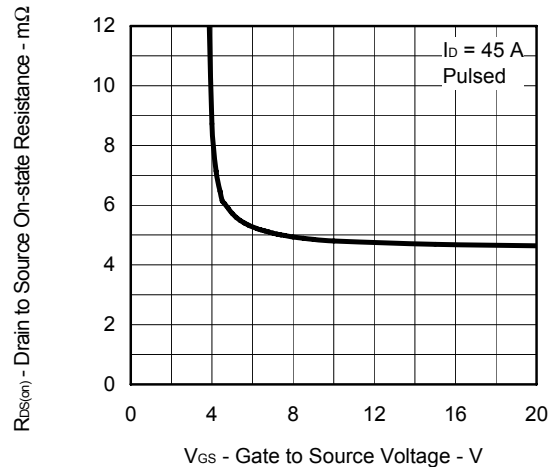
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



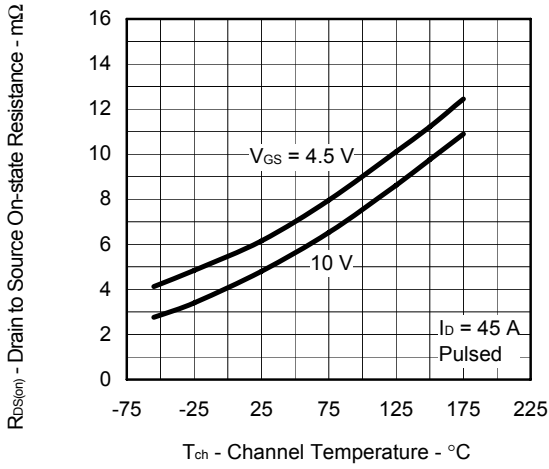
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



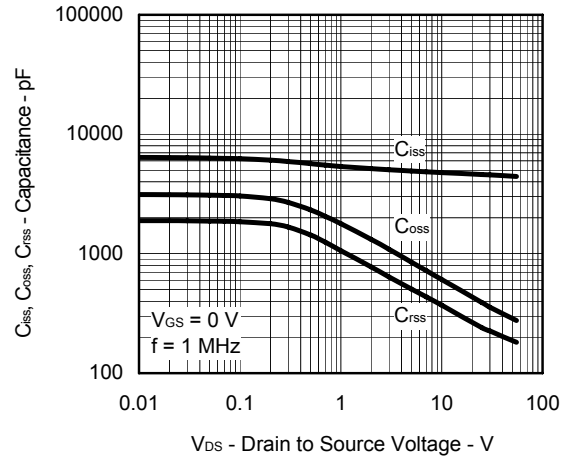
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



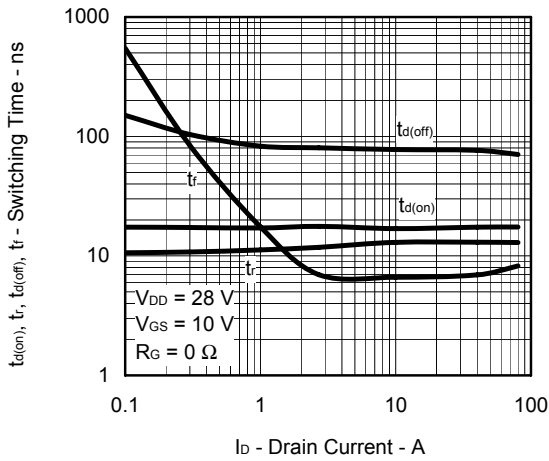
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



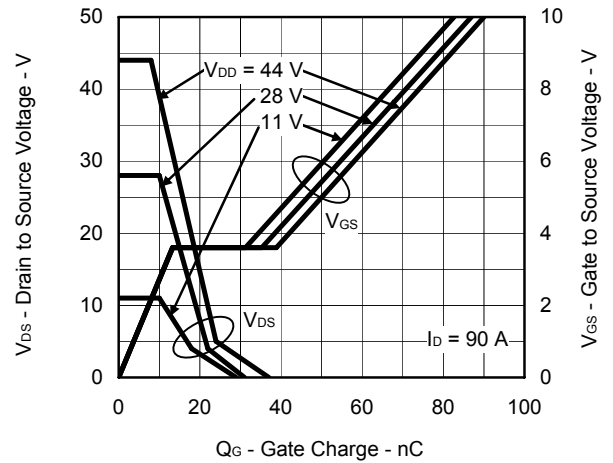
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



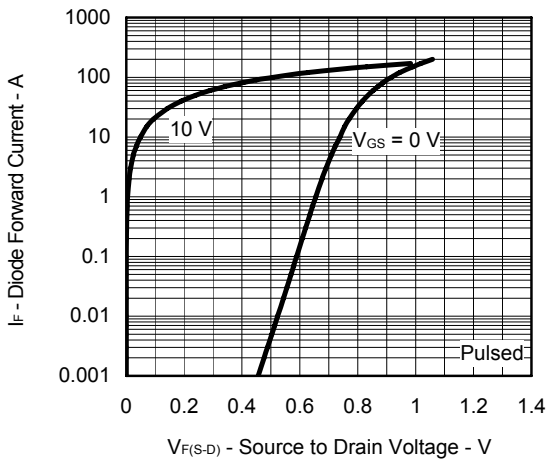
SWITCHING CHARACTERISTICS



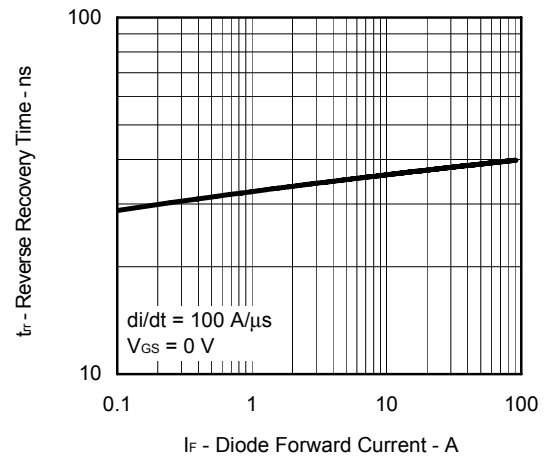
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

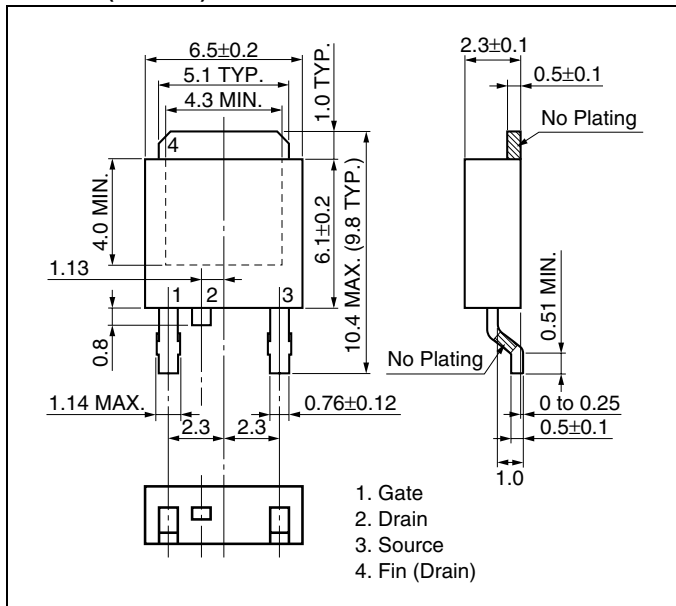


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

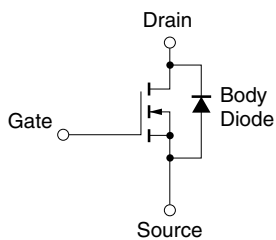


PACKAGE DRAWING (Unit: mm)

TO-252 (MP-3ZP)



EQUIVALENT CIRCUIT

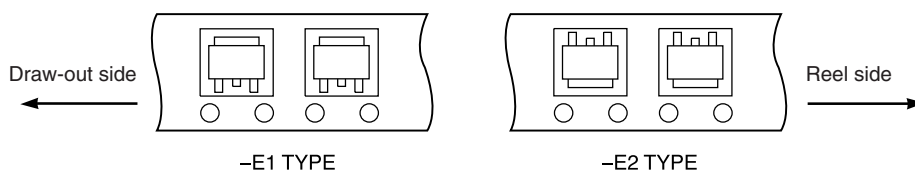


**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

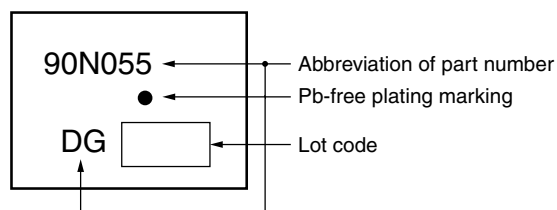


**TAPE INFORMATION**

There are two types (-E1, -E2) of taping depending on the direction of the device.



**MARKING INFORMATION**



**RECOMMENDED SOLDERING CONDITIONS**

The NP90N055VDG should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

| Soldering Method | Soldering Conditions   | Recommended Condition Symbol |
|------------------|--|------------------------------|
| Infrared reflow  | Maximum temperature (Package's surface temperature): 260°C or below<br>Time at maximum temperature: 10 seconds or less<br>Time of temperature higher than 220°C: 60 seconds or less<br>Preheating time at 160 to 180°C: 60 to 120 seconds<br>Maximum number of reflow processes: 3 times<br>Maximum chlorine content of rosin flux (percentage mass): 0.2% or less | IR60-00-3                    |
| Partial heating  | Maximum temperature (Pin temperature): 350°C or below<br>Time (per side of the device): 3 seconds or less<br>Maximum chlorine content of rosin flux: 0.2% (wt.) or less  | P350                         |

**Caution Do not use different soldering methods together (except for partial heating).**

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